# 826947-8 - ACTIVE

#### AMPMODU | AMPMODU Headers

TE Internal #: 826947-8 PCB Mount Header, Right Angle, Board-to-Board, 8 Position, .1 in [2.54 mm] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers

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#### Connectors > PCB Connectors > PCB Headers & Receptacles



### PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Right Angle

Connector System: Board-to-Board

Number of Positions: 8

Number of Rows: 1

### Features

### Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Breakaway



Sealable	No			
Connector & Contact Terminates To	Printed Circuit Board			
Configuration Features				
Connector Contact Load Condition	Fully Loaded			
PCB Mount Orientation	Right Angle			
Number of Positions	8			
Number of Rows	1			
Board-to-Board Configuration	Perpendicular			
Electrical Characteristics				
Insulation Resistance	5000 MΩ			
Dielectric Withstanding Voltage (Max)	750 Vrms			
Body Features				
Primary Product Color	Green			
Contact Features				
Mating Square Post Dimension	.64 mm[.025 in]			

**C** For support call+1 800 522 6752

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PCB Contact Termination Area Plating Material Thickness	2 µm		
Contact Shape & Form	Square		
Contact Underplating Material	Nickel		
PCB Contact Termination Area Plating Material	Tin		
Contact Base Material	Phosphor Bronze		
Contact Mating Area Plating Material	Tin		
Contact Mating Area Plating Material Thickness	3 μm[118.11 μin]		
Contact Type	Pin		
Contact Current Rating (Max)	5 A		
Termination Features			
Square Termination Post & Tail Dimension	.64 mm[.025 in]		
Termination Post & Tail Length	3.2 mm[.126 in]		
Termination Method to Printed Circuit Board	Through Hole - Solder		
Mechanical Attachment			
Mating Alignment	Without		
PCB Mount Retention	Without	Without	
PCB Mount Alignment	Without		
Connector Mounting Type	Board Mount		
Housing Features			
Centerline (Pitch)	2.54 mm[.1 in]		
Housing Material	PBT		
Dimensions			
PCB Thickness (Recommended)	1.57 mm[.062 in]	1.57 mm[.062 in]	
Usage Conditions			
Housing Temperature Rating	Standard		
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]		
Operation/Application			
Circuit Application	Signal		
Industry Standards			
UL Flammability Rating	UL 94V-0		
Packaging Features			
Packaging Quantity	400		
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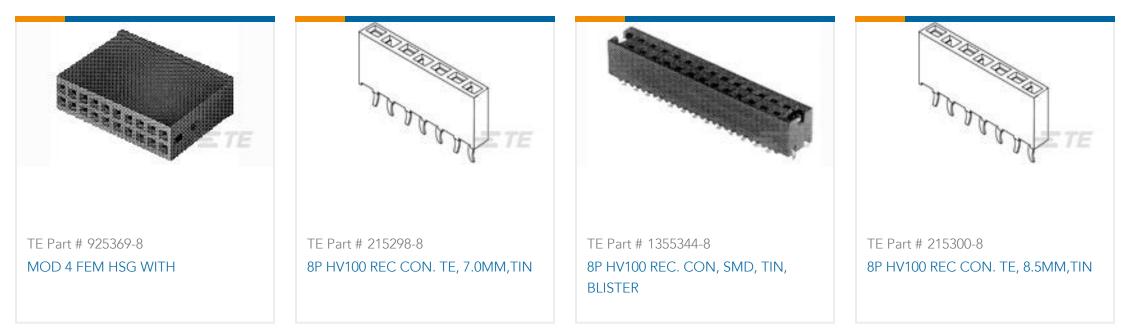


Packaging Type Box **Product Compliance** For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU Compliant Compliant EU ELV Directive 2000/53/EC No Restricted Materials Above Threshold China RoHS 2 Directive MIIT Order No 32, 2016 EU REACH Regulation (EC) No. 1907/2006 Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2021 (211) SVHC > Threshold: Not Yet Reviewed Halogen Content Not Low Halogen - contains Br or Cl > 900 ppm. Solder Process Capability Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## **Compatible Parts**

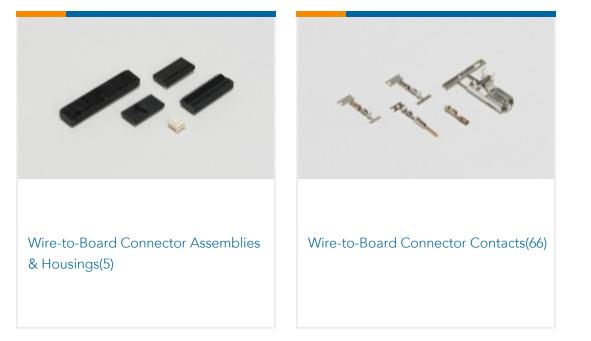


## Also in the Series AMPMODU Headers

PCB Mount Header, Right Angle, Board-to-Board, 8 Position, .1 in [2.54 mm] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers







# Customers Also Bought



10 MODII HDR DRST SHRD .100CL	2X4P HV100 REC CON. TE, 8.5MM	STANDARD EDGE .050 SERIES 60 DUAL ASSY	MINI UMNL SOK 26-22 AWG AU LF
TE			
TE Part #1-794226-0 MINI UMNL2 PIN 26-22AWG LP LF	TE Part #826656-3 3P AMPMODU II STIFT LEI	TE Part #1-1393586-8 V23535A2200A260=BKMOD421 HEADE	TE Part #1393558-3 C42334A 421C 41 *Z150

TE Part #1393558-5 C42334A 421C 51 \*Z150

### Documents

PCB Mount Header, Right Angle, Board-to-Board, 8 Position, .1 in [2.54 mm] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers



Product Drawings 8P MOD2 STIFT LEI

English

8P MOD2 STIFT LEI

English

### **CAD** Files

### 3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_826947-8\_M.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_826947-8\_M.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_826947-8\_M.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Agency Approvals UL Report

English